

N-type-G12-R (182.3×210*272) A

Monocrystalline Wafer





The file version

PN testing machine

Phos.()

Ω -cm

Wafer inspection system

Lifetime/ μ $\geq$

Oxygen concentration/ppma $\leq$

Carbon Concentration /ppma $\leq$

Growth method

Etch pit density (dislocation density)/pcs/cm² $\leq$

Surface orientation/°

Orientation of pseudo square sides/°

Wafer model

Geometry

Wafer Side length/mm

Wafer Diameter/mm

Arc length projection/mm

Angle between adjacent sides/°

μ m

Batch mean/ μ m $\geq$

μ m $\leq$

μ m $\leq$

μ m $\leq$

μ m $\leq$

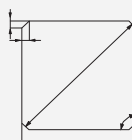
Cutting method

No visual defects (no stains no finger prints no oil no glue).

≤ 0.3 mm , Length ≤ 0.5 mm
 $\leq$

Naked eyes or wafer inspection system

Schematic diagram of wafer size



A.Shape/Size 182.3/210 $\pm$ 0.25 mm

B.Diagonal 272 $\pm$ 0.25 mm

C.Corner Length 4.72/4.07 $\pm$ 0.5 mm

D.Right Angle 90 $\pm$ 0.15°